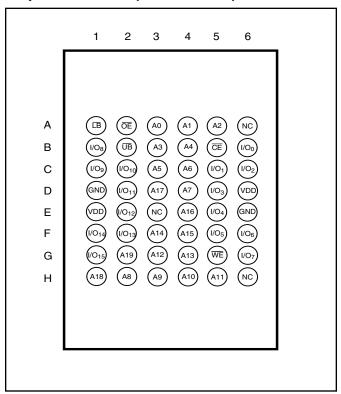


48-pin mini BGA (9mmx11mm)

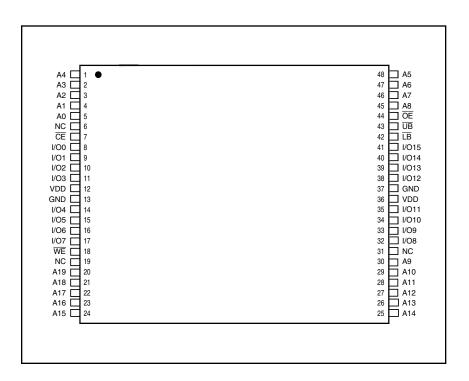


PIN DESCRIPTIONS

A0-A19	Address Inputs			
I/O0-I/O15	Data Inputs/Outputs			
CE	Chip Enable Input			
ŌĒ	Output Enable Input			
WE	Write Enable Input			
LB	Lower-byte Control (I/O0-I/O7)			
ŪB	Upper-byte Control (I/O8-I/O15)			
NC	No Connection			
V _{DD}	Power			
GND	Ground			



48-pin TSOP-I (12mm x 20mm)



PIN DESCRIPTIONS

A0-A19	Address Inputs			
I/O0-I/O15	Data Inputs/Outputs			
CE	Chip Enable Input			
ŌĒ	Output Enable Input			
WE	Write Enable Input			
LB	Lower-byte Control (I/O0-I/O7)			
ŪB	Upper-byte Control (I/O8-I/O15)			
NC	No Connection			
V _{DD}	Power			
GND	Ground			



TRUTH TABLE

						I/O	PIN	
Mode	WE	CE	ŌĒ	ĪΒ	$\overline{\sf UB}$	1/00-1/07	I/O8-I/O15	VDD Current
Not Selected	Х	Н	Χ	Χ	Χ	High-Z	High-Z	ISB1, ISB2
Output Disabled	Н	L	Н	Х	Х	High-Z	High-Z	Icc
	Χ	L	Χ	Н	Н	High-Z	High-Z	
Read	Н	L	L	L	Н	D out	High-Z	Icc
	Н	L	L	Н	L	High-Z	D ouт	
	Н	L	L	L	L	D out	D оит	
Write	L	L	Х	L	Н	Din	High-Z	Icc
	L	L	Χ	Н	L	High-Z	DIN	
	L	L	Χ	L	L	DIN	DIN	

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameter	Value	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to V _{DD} + 0.5	V
VDD	VDD Relates to GND	-0.3 to 4.0	V
Тѕтс	Storage Temperature	-65 to +150	°C
Рт	Power Dissipation	1.0	W

Notes:

CAPACITANCE(1,2)

Symbol	Parameter	Conditions	Max.	Unit	
Cin	Input Capacitance	VIN = 0V	6	pF	
C _{I/O}	Input/Output Capacitance	VOUT = $0V$	8	pF	

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions: $TA = 25^{\circ}C$, f = 1 MHz, VDD = 3.3V.

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



OPERATING RANGE (VDD) (IS61WV102416ALL)

Range	Ambient Temperature	V _{DD} (20 ns)	
Commercial	0°C to +70°C	1.65V-2.2V	
Industrial	–40°C to +85°C	1.65V-2.2V	
Automotive	-40°C to +125°C	1.65V-2.2V	

OPERATING RANGE (VDD) (IS61WV102416BLL)(1)

Range	Ambient Temperature	Vdd (8 ns)	V _{DD} (10 ns)	
Commercial	0°C to +70°C	3.3V <u>+</u> 5%	2.4V-3.6V	
Industrial	–40°C to +85°C	3.3V <u>+</u> 5%	2.4V-3.6V	

Note:

OPERATING RANGE (VDD) (IS64WV102416BLL)

Range	Ambient Temperature	V _{DD} (10 ns)
Automotive	-40°C to +125°C	2.4V-3.6V

^{1.} When operated in the range of 2.4V-3.6V, the device meets 10ns. When operated in the range of $3.3V \pm 5\%$, the device meets 8ns.



DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

$V_{DD} = 3.3V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Vон	Output HIGH Voltage	$V_{DD} = Min., IoH = -4.0 mA$	2.4	_	V
Vol	Output LOW Voltage	$V_{DD} = Min., IoL = 8.0 mA$	_	0.4	V
VIH	Input HIGH Voltage		2	$V_{DD} + 0.3$	V
VIL	Input LOW Voltage(1)		-0.3	0.8	V
Iμ	Input Leakage	$GND \leq Vin \leq Vdd$	-1	1	μΑ
ILO	Output Leakage	GND ≤ Vouт ≤ Vdd, Outputs Disabled	-1	1	μΑ

Note:

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

$V_{DD} = 2.4V - 3.6V$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Vон	Output HIGH Voltage	$V_{DD} = Min., IOH = -1.0 mA$	1.8	_	V
Vol	Output LOW Voltage	VDD = Min., IOL = 1.0 mA	_	0.4	V
VIH	Input HIGH Voltage		2.0	$V_{DD} + 0.3$	V
VIL	Input LOW Voltage(1)		-0.3	0.8	V
ILI	Input Leakage	$GND \leq V IN \leq V DD$	-1	1	μA
ILO	Output Leakage	GND ≤ Vout ≤ VDD, Outputs Disabled	-1	1	μA

Note:

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

$V_{DD} = 1.65V-2.2V$

Symbol	Parameter	Test Conditions	V DD	Min.	Max.	Unit
Vон	Output HIGH Voltage	Iон = -0.1 mA	1.65-2.2V	1.4	<u> </u>	V
Vol	Output LOW Voltage	lol = 0.1 mA	1.65-2.2V	_	0.2	V
VIH	Input HIGH Voltage		1.65-2.2V	1.4	VDD + 0.2	V
VIL ⁽¹⁾	Input LOW Voltage		1.65-2.2V	-0.2	0.4	V
lu	Input Leakage	$GND \leq V IN \leq V DD$		-1	1	μA
ILO	Output Leakage	GND ≤ Vout ≤ Vdd, Out	puts Disabled	-1	1	μΑ

V_{IL} (min.) = -0.3V DC; V_{IL} (min.) = -2.0V AC (pulse width 2.0 ns). Not 100% tested.
 V_{IH} (max.) = V_{DD} + 0.3V DC; V_{IH} (max.) = V_{DD} + 2.0V AC (pulse width 2.0 ns). Not 100% tested.

^{1.} V_{IL} (min.) = −0.3V DC; V_{IL} (min.) = −2.0V AC (pulse width 2.0 ns). Not 100% tested. V_{IH} (max.) = V_{DD} + 0.3V DC; V_{IH} (max.) = V_{DD} + 2.0V AC (pulse width 2.0 ns). Not 100% tested.

VIL (min.) = -0.3V DC; VIL (min.) = -2.0V AC (pulse width -2.0ns). Not 100% tested.
 VIH (max.) = VDD + 0.3V DC; VIH (max.) = VDD + 2.0V AC (pulse width -2.0ns). Not 100% tested.



ACTEST CONDITIONS (HIGH SPEED)

Parameter	Unit (2.4V-3.6V)	Unit (3.3V <u>+</u> 5%)	Unit (1.65V-2.2V)
Input Pulse Level	0.4V to VDD-0.3V	0.4V to V _{DD} -0.3V	0.4V to VDD-0.2V
Input Rise and Fall Times	1.5ns	1.5ns	1.5ns
Input and Output Timing and Reference Level (VRef)	VDD/2	VDD/2 + 0.05	V _{DD} /2
Output Load	See Figures 1 and 2	See Figures 1 and 2	See Figures 1 and 2

ACTEST LOADS

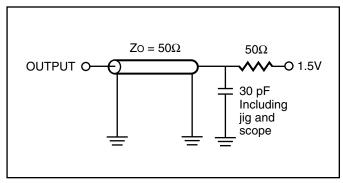


Figure 1.

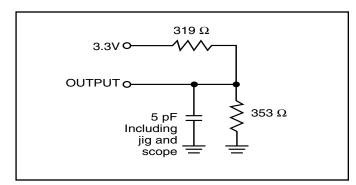


Figure 2.



POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

				-	8	-1	0	-2	.0	
Symbol	Parameter	Test Conditions		Min.	Max.	Min.	Max.	Min.	Max.	Unit
Icc	VDD Dynamic Operating	VDD = Max.,	Com.	_	110	_	90	_	50	mA
	Supply Current	IOUT = 0 mA, f = fMAX	Ind.	_	115	_	95	_	60	
		$V_{IN} = 0.4V$ or $V_{DD} = -0.3V$	Auto.	_	_	_	140	_	100	
			typ.(2)			60)			
lcc1	Operating	V _{DD} = Max.,	Com.	_	85	_	85	_	45	mA
	Supply Current	IOUT = 0 mA, f = 0	Ind.	_	90	_	90	_	55	
		$V_{IN} = 0.4V$ or $V_{DD} - 0.3V$	Auto.	_	_	_	110	_	90	
ISB1	TTL Standby Current	V _{DD} = Max.,	Com.	_	30	_	30	_	30	mA
	(TTL Inputs)	VIN = VIH Or VIL	Ind.	_	35	_	35	_	35	
		$\overline{CE} \ge V_{IH}, f = 0$	Auto.	_	_	_	70	_	70	
IsB2	CMOS Standby	V _{DD} = Max.,	Com.	_	20	_	20	_	20	mA
	Current (CMOS Inputs)	$\overline{CE} \ge V_{DD} - 0.2V$,	Ind.	_	25	_	25	_	25	
	. ,	$V_{IN} \ge V_{DD} - 0.2V$, or	Auto.	_	_	_	60	_	60	
		$Vin \leq \ 0.2V, f=0$	typ.(2)			4	•			

^{1.} At f = fmax, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

^{2.} Typical values are measured at $V_{DD} = 3.0V$, $T_A = 25^{\circ}C$ and not 100% tested.



READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

		-	8	-1	10	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
trc	Read Cycle Time	8	_	10	_	ns
taa	Address Access Time	_	8	_	10	ns
t oha	Output Hold Time	2.5	_	2.5	_	ns
tace	CE Access Time	_	8	_	10	ns
tDOE	OE Access Time	_	5.5	_	6.5	ns
thzoe(2)	OE to High-Z Output	_	3	_	4	ns
tLZOE ⁽²⁾	OE to Low-Z Output	0	_	0	_	ns
thzce(2	CE to High-Z Output	0	3	0	4	ns
tLZCE ⁽²⁾	CE to Low-Z Output	3	_	3	_	ns
tва	LB, UB Access Time	_	5.5	_	6.5	ns
t _{HZB⁽²⁾}	LB, UB to High-Z Output	0	3	0	3	ns
tLZB ⁽²⁾	LB, UB to Low-Z Output	0	_	0	_	ns
tpu	Power Up Time	0	_	0	_	ns
t PD	Power Down Time		8	_	10	ns

^{1.} Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.

^{2.} Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage.



READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

	-20 ns					
Symbol	Parameter	Min.	Max.	Unit		
t RC	Read Cycle Time	20	_	ns		
t AA	Address Access Time	_	20	ns		
t oha	Output Hold Time	2.5	_	ns		
t ACE	CE Access Time	_	20	ns		
tdoe	OE Access Time	_	8	ns		
thzoe(2)	OE to High-Z Output	0	8	ns		
tLZOE ⁽²⁾	OE to Low-Z Output	0	_	ns		
thzce(2	CE to High-Z Output	0	8	ns		
tLZCE ⁽²⁾	CE to Low-Z Output	3	_	ns		
t BA	LB, UB Access Time	<u> </u>	8	ns		
tнzв	LB, UB to High-Z Output	0	8	ns		
t LZB	LB, UB to Low-Z Output	0	_	ns		

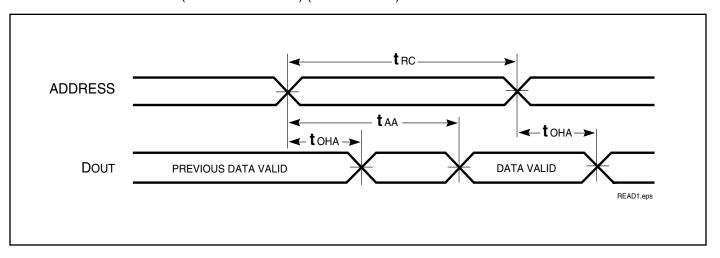
^{1.} Test conditions assume signal transition times of 1.5 ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to VDD-0.3V and output loading specified in Figure 1a.

^{2.} Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.

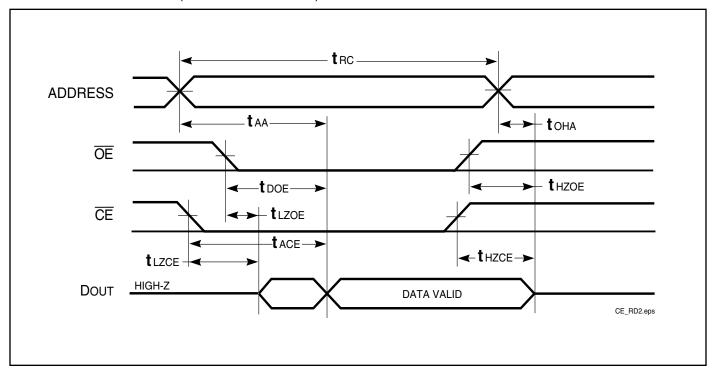
^{3.} Not 100% tested.



AC WAVEFORMS READ CYCLE NO. $1^{(1,2)}$ (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$)



READ CYCLE NO. 2^(1,3) ($\overline{\text{CE}}$ and $\overline{\text{OE}}$ Controlled)



- 1. $\overline{\text{WE}}$ is HIGH for a Read Cycle.
- The device is continuously selected. OE, CE = VIL.
 Address is valid prior to or coincident with CE LOW transitions.



WRITE CYCLE SWITCHING CHARACTERISTICS(1,3) (Over Operating Range)

		-8		-10	
Symbol	Parameter	Min.	Max.	Min. Max.	Unit
twc	Write Cycle Time	8	_	10 —	ns
tsce	CE to Write End	6.5	_	8 —	ns
taw	Address Setup Time to Write End	6.5	_	8 —	ns
tна	Address Hold from Write End	0	_	0 —	ns
t sa	Address Setup Time	0	_	0 —	ns
t pwB	LB, UB Valid to End of Write	6.5	_	8 —	ns
t PWE1	WE Pulse Width	6.5	_	8 —	ns
tpwe2	WE Pulse Width (OE = LOW)	8.0	_	10 —	ns
t sd	Data Setup to Write End	5	_	6 —	ns
t HD	Data Hold from Write End	0	_	0 —	ns
thzwe ⁽²⁾	WE LOW to High-Z Output	_	3.5	– 5	ns
tLZWE ⁽²⁾	WE HIGH to Low-Z Output	2	_	2 —	ns

^{1.} Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.

^{2.} Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.

^{3.} The internal write time is defined by the overlap of CE LOW and UB or LB, and WE LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write. Shaded area product in development



WRITE CYCLE SWITCHING CHARACTERISTICS(1,2) (Over Operating Range)

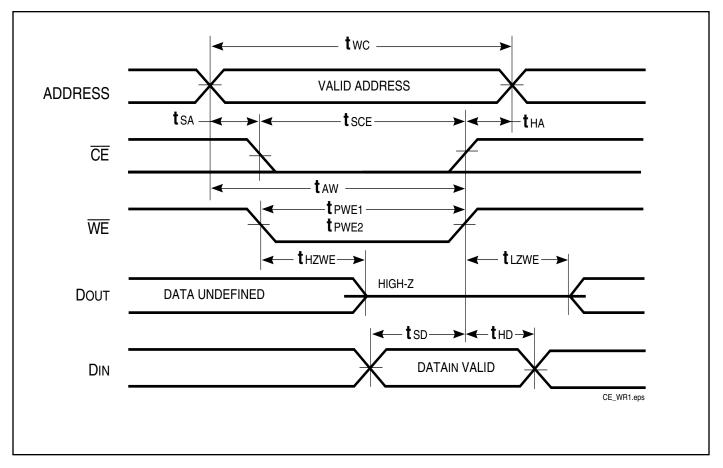
	-20 ns			
Symbol	Parameter	Min.	Max.	Unit
twc	Write Cycle Time	20	_	ns
tsce	CE to Write End	12	_	ns
taw	Address Setup Time to Write End	12	_	ns
t HA	Address Hold from Write End	0	_	ns
t sA	Address Setup Time	0	_	ns
t PWB	LB, UB Valid to End of Write	12	_	ns
tpwe1	$\overline{\text{WE}}$ Pulse Width ($\overline{\text{OE}}$ = HIGH)	12	_	ns
tPWE2	$\overline{\text{WE}}$ Pulse Width ($\overline{\text{OE}}$ = LOW)	17	_	ns
t sd	Data Setup to Write End	9	_	ns
t HD	Data Hold from Write End	0	_	ns
thzwe ⁽³⁾	WE LOW to High-Z Output	_	9	ns
tLZWE ⁽³⁾	WE HIGH to Low-Z Output	3		ns

- 1. Test conditions for IS61WV6416LL assume signal transition times of 1.5ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to VDD-0.3V and output loading specified in Figure 1a.
- 2. Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
- 3. The internal write time is defined by the overlap of CE LOW and UB or LB, and WE LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.



AC WAVEFORMS

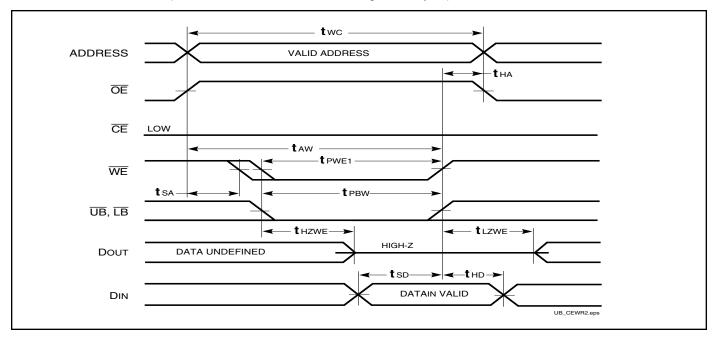
WRITE CYCLE NO. $1^{(1,2)}$ (\overline{CE} Controlled, \overline{OE} = HIGH or LOW)



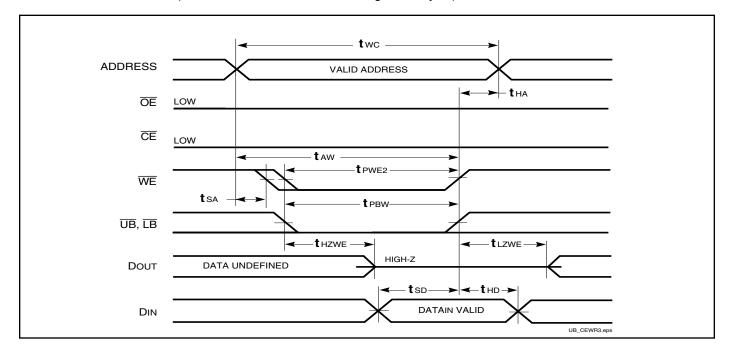


AC WAVEFORMS

WRITE CYCLE NO. 2 (WE Controlled. OE is HIGH During Write Cycle) (1,2)



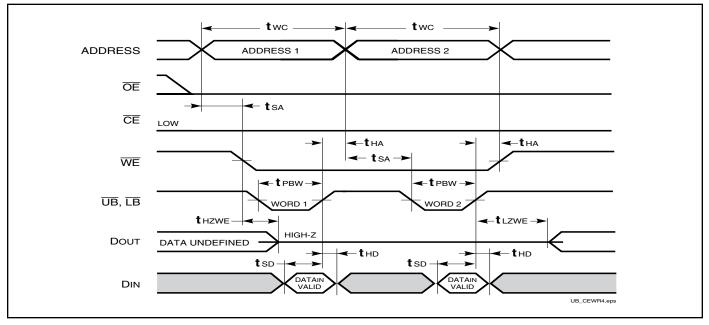
WRITE CYCLE NO. 3 (WE Controlled. OE is LOW During Write Cycle) (1)





AC WAVEFORMS

WRITE CYCLE NO. 4 (LB, UB Controlled, Back-to-Back Write) (1,3)



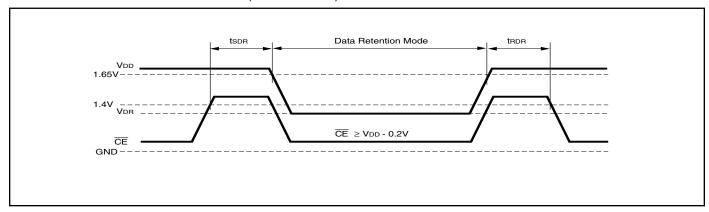
- 1. The internal Write time is defined by the overlap of $\overline{CE} = LOW$, \overline{UB} and/or $\overline{LB} = LOW$, and $\overline{WE} = LOW$. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The t_{SA} , t_{HA} , t_{SD} , and t_{HD} timing is referenced to the rising or falling edge of the signal that terminates the Write.
- 2. Tested with \overline{OE} HIGH for a minimum of 4 ns before \overline{WE} = LOW to place the I/O in a HIGH-Z state.
- 3. WE may be held LOW across many address cycles and the LB, UB pins can be used to control the Write function.



DATA RETENTION SWITCHING CHARACTERISTICS

Symbol	Parameter	Test Condition		Min.	Max.	Unit
VDR	VDD for Data Retention	See Data Retention Waveform		1.2	3.6	V
IDR	Data Retention Current	$V_{DD} = 1.2V, \overline{CE} \ge V_{DD} - 0.2V$	Ind. Auto.		20 50	mA
tsdr	Data Retention Setup Time	See Data Retention Waveform		0	_	ns
trdr	Recovery Time	See Data Retention Waveform		t RC	_	ns

DATA RETENTION WAVEFORM (CE Controlled)





ORDERING INFORMATION

Industrial Range: -40°C to +85°C Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10 (8¹)	IS61WV102416BLL-10MI	48 mini BGA (9mm x 11mm)
	IS61WV102416BLL-10MLI	48 mini BGA (9mm x 11mm), Lead-free
	IS61WV102416BLL-10TLI	TSOP (Type I), Lead-free

Note:

Industrial Range: -40°C to +85°C Voltage Range: 1.65V to 2.2V

Speed (ns)	Order Part No.	Package
20	IS61WV102416ALL-20MI	48 mini BGA (9mm x 11mm)
	IS61WV102416ALL-20MLI	48 mini BGA (9mm x 11mm), Lead-free
	IS61WV102416ALL-20TLI	TSOP (Type I), Lead-free

Automotive Range: -40°C to +125°C

Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10	IS64WV102416BLL-10MA3	48 mini BGA (9mm x 11mm)
	IS64WV102416BLL-10MLA3	48 mini BGA (9mm x 11mm), Lead-free
	IS64WV102416BLL-10CTLA3	TSOP (Type I), Copper Leadframe, Lead-free

^{1.} Speed = 8ns for V_{DD} = 3.3V \pm 5%. Speed = 10ns for V_{DD} = 2.4V - 3.6V



